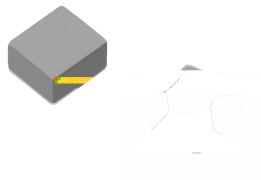
MDA Series

SMD Low Profile High Current Molded Inductor

Size 252010



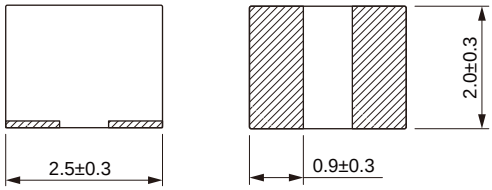
FEATURES

- High current, low DCR,high e ciency.
- Very low acous c noise and very low leakage flux noise.
- AEC-Q200 qualified
- 100% Lead(Pb)-Free and RoHS compliant.
- Opera ng temperature: -55 to +150 °C (including self-temperature rise)
- Quan ty: 3000PCS

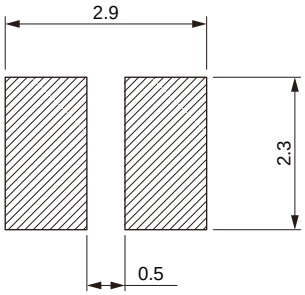
APPLICATION

- Headlamps, tail lamps and interior ligh ng
- HVAC
- Doors, window li and seat control
- Audio subsystem
- Digital instrument cluster
- In-Vehicle Infotainment and naviga on

Dimensions: [mm]



Land Pattern: [mm]



Electrical Properties:

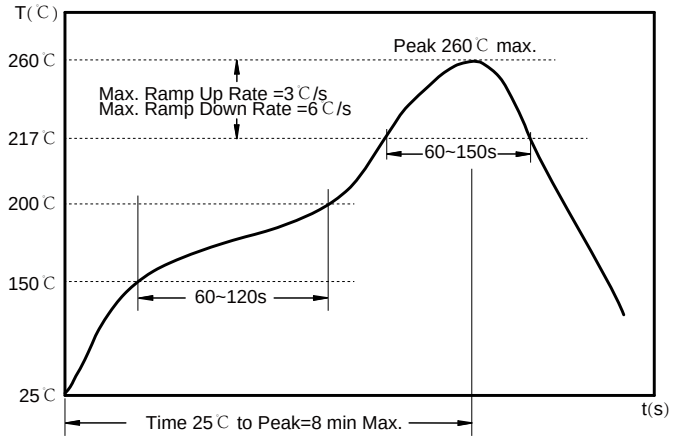
Part No	Inductance @ 1MHz/1V (μH)	Tolerance	Temperature Rise Current Typ. (A)	Temperature Rise Current Max. (A)	Satura on Current Typ. (A)	Satura on Current Max. (A)	DC Resistance Typ. (mΩ)	DC Resistance Max. (mΩ)
MDA252010-R33M	0.33	±20%	6.6	6.2	7.6	7.2	13	17
MDA252010-R68M	0.68	±20%	5.6	5.0	5.9	5.5	23	27
MDA252010-1R0M	1.00	±20%	4.5	4.1	5.3	4.8	24	28
MDA252010-2R2M	2.20	±20%	2.9	2.6	3.4	3.0	57	66
MDA252010-3R3M	3.30	±20%	2.5	2.2	2.8	2.5	86	100
MDA252010-4R7M	4.70	±20%	2.0	1.6	2.6	2.0	180	216
MDA252010-100M	10.0	±20%	1.2	1.1	1.6	1.4	490	520

Saturation Current will cause L to drop approximately 30%

Temperature Rise Current: The actual value of DC current when the temperature rise is △T=40°C

KOHER Electronic
4546 BATES DRIVE, YORBLINDA CA 92886 USA
714-325-4789 Contact@kohergroup.com

Soldering Reflow:



Preheat condition: 150 ~200℃/ 60~120 sec.

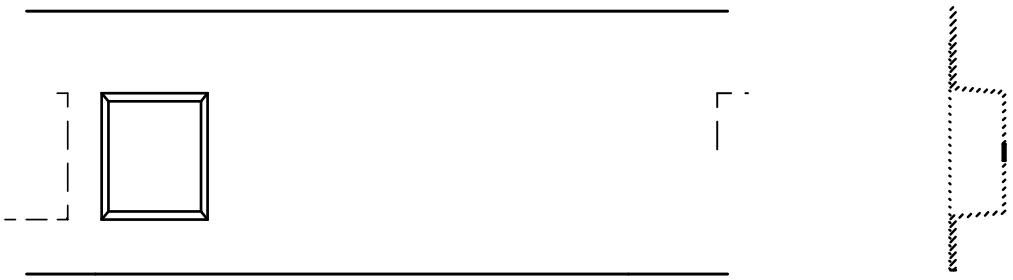
Allowed time above 217℃: 60~150 sec.

Max temperature: 260℃.

Allowed Reflow time: 3x max.

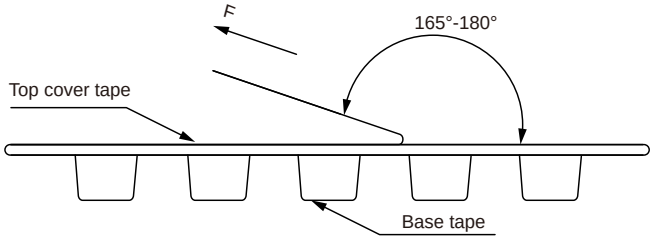
Packaging Information:

Tape Dimension:



Series	A0 (mm)	B0 (mm)	D (mm)	P0 (mm)	P1 (mm)	W (mm)	K0 (mm)	E (mm)	T (mm)
MDA252010	2.4 ± 0.1	2.9 ± 0.1	1.5 ± 0.1	4.0 ± 0.1	4.0 ± 0.1	8.0 ± 0.3	1.2 ± 0.1	1.75 ± 0.1	0.25 ± 0.05

Peel force of top cover tape:

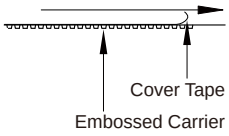


The peel force of top cover tape shall be between 0.1 to 0.98 N

etc.

Reel Dimension：[mm]

Product should not be exposed to environment with high temperature, high humidity, dust, corrosive gas and



Packaging Quantity: